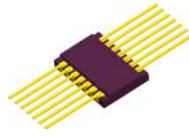


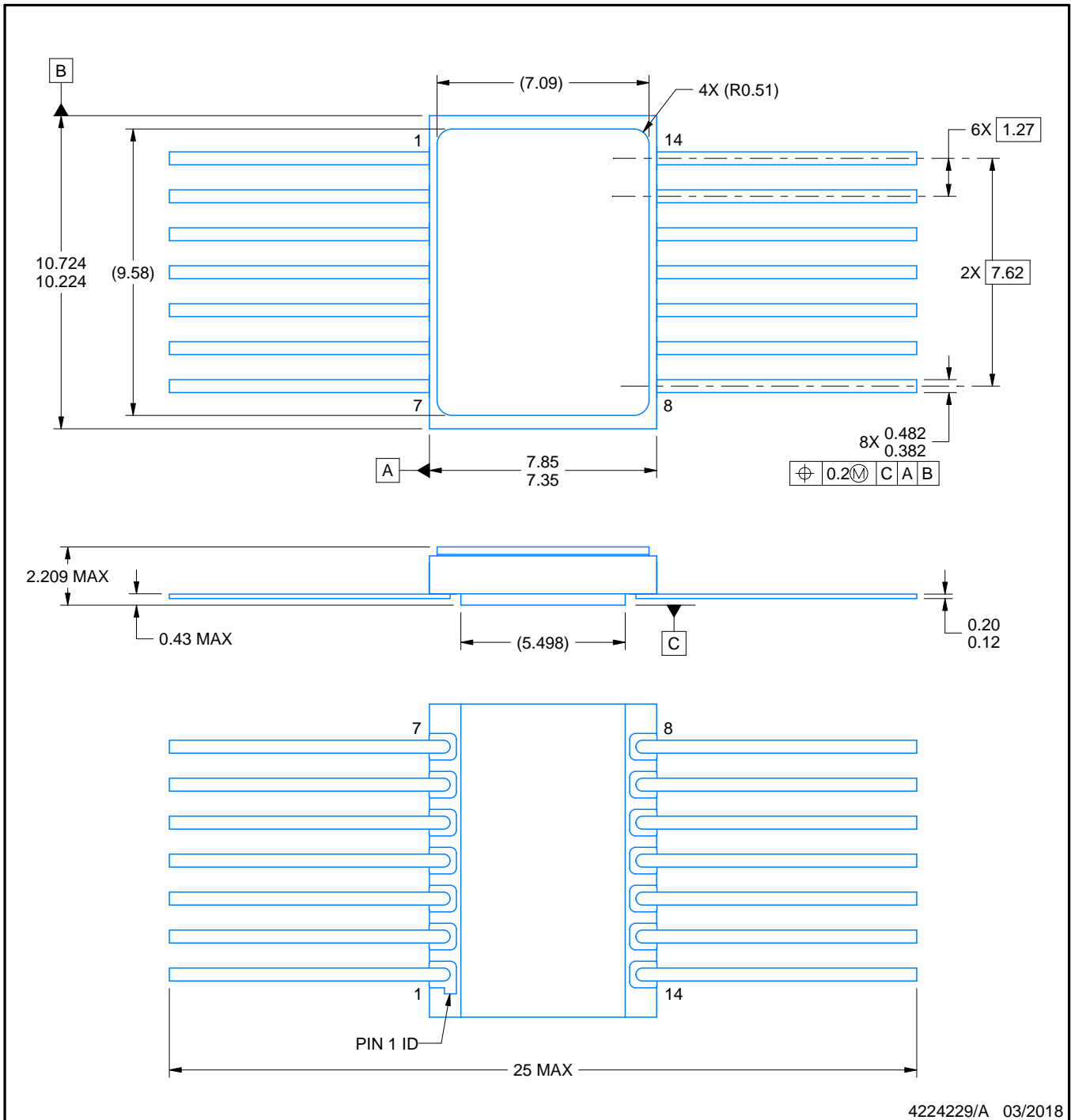
HFR0014A



PACKAGE OUTLINE

CFP - 2.209 mm max height

CERAMIC FLATPACK



4224229/A 03/2018

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. The lid is not connected to any lead.
4. The leads are gold plated.

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